

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	107	chemical adj mechanical adj polishing.ti. and seed and barrier	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/08 14:41
L2	90	chemical adj mechanical adj polishing.ti. and seed and barrier and interconnect\$3	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/08 14:49
L3	18	electrochemical adj mechanical adj polishing.ti. and volt	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/08 14:50
S1	5	("6096648" "6242343" "6285035" "6315883" "6368190").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/08 14:41
S2	174457	abrasive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/23 19:49
S3	3	S1 and S2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/23 19:51
S4	672078	pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/23 19:51
S5	3	S1 and S2 and S3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/23 19:51
S6	3	S1 and S2 and S4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/23 19:57
S7	225	(205/663).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/23 19:57

EAST Search History

S8	18	S2 and S4 and S7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/23 19:58
S9	23	S4 and S7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/23 20:24
S10	39363	conduct\$3 near3 pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/23 20:28
S11	9	S7 and S10	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/23 20:24
S12	392	conduct\$3 near3 pad near3 polish\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/23 20:28
S13	3449	(205/640-686).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/23 20:28
S14	50	S12 and S13	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 10:27
S15	392	conduct\$3 near3 pad near3 polish\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 10:27

EAST Search History

S16	3449	(205/640-686).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/24 10:27
S17	50	S15 and S16	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 11:12
S18	2	("20030114087").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/24 11:18
S19	21	seed and abrasive and S17	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 11:18
S20	748	ecmp electrochemical adj mechanical	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/08 12:39
S21	459	ecmp electrochemical adj mechanical with (polish\$3 etch\$3 planariz\$5)	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/08 12:39